EE 505 Lecture 12

DAC Design

- DAC Architectures
- Sring DACs

Review from last lecture

Random Offset Voltages

Typical offset voltages:

MOS - 5mV to 50MV BJT - 0.5mV to 5mV

These can be scaled with extreme device dimensions

Often more practical to include offset-compensation circuitry

Summary of Offset Voltage Issues Review from last lecture

- Random offset voltage is generally dominant and due to mismatch in device and model parameters
- MOS Devices have large V_{OS} if area is small
- σ decreases approximately with $1/\sqrt{A}$
- Multiple fingers for MOS devices offer benefits for common centroid layouts but too many fingers will ultimately degrade offset because perimeter/area ration will increase $(A_{W}$ and A_{L} will become of concern)
- Offset voltage of dynamic comparators is often large and analysis not straightforward

n ⊢n Pn W_n L_p

• Offset compensation often used when low offsets important 2 $2 \sim$ 1 \sim VTO n H P \sim 1 n \sim 1 2 V 2 VTO p A²_{VTO p} μ_{D} L σ 2 + A W_n L_n μ_n W_n L^2 $\begin{bmatrix} 2 & 1 & 1 & 1 \end{bmatrix}$ \approx 2 $\frac{\text{N} \cdot \text{N} - \mu \cdot \text{N}}{2}$ $\lfloor W_n L_n \mu_n W_n L_p^{2} \rfloor$ MOS:

$$
\begin{array}{ll}\n\text{Bipolar:} & \sigma_{V_{OS}}^2 \equiv 2V_t^2 \left[\frac{A_{\text{Jn}}^2}{A_{\text{En}}} + \frac{A_{\text{Jp}}^2}{A_{\text{Ep}}} \right]\n\end{array}
$$

OS

Types (Nyquist Rate)

- Voltage Scaling
	- Resistor String DACs (string DACs)
	- Interpolating
- Current Steering
	- Binary Weighted Resistors
	- R-2R Ladders
	- Current Source Steering
		- Thermometer Coded
		- Binary Weighted
		- Segmented
- Charge Redistribution
	- Switched Capacitor
- Serial
	- Algorithmic
	- Cyclic or Re-circulating
	- Pipelined
- Integrating
- Resistor Switching
- MDACs (multiplying DACs)

Observations

- Yield Loss is the major penalty for not appropriately managing parasitics and matching and this loss can be ruthless
- The ultimate performance limit of essentially all DACs is the yield loss associated with parasitics and matching
- Many designers do not have or use good statistical models that accurately predict data converter performance
- If you work of a company that does not have good statistical device models
	- Convince model groups of the importance of developing these models
	- (or) develop appropriate test structures to characterize your process
- Existing nonlinear device models may not sufficiently accurately predict device nonlinearities for high-end data converter applications

Structures

- Hybrid or Segmented
- Mode of Operation
	- Current Mode
	- Voltage Mode
	- Charge Mode
- Self-Calibrating
	- Analog Calibration
		- Foreground
		- Background
	- Digital Calibration
		- Foreground
		- Background
	- Dynamic Element Matching
- Laser or Link Trimmed
- Thermometer Coded or Binary
- Radix 2 or non-radix 2
- Inherently Monotone

- Type of Classification may not be unique nor mutually exclusive
- Structure is not mutually exclusive
- All approaches listed are used (and probably some others as well)
- Some are much more popular than others
	- Popular Architectures
		- Resistor String (interpolating)
		- Current Source Steering (with segmentation)
		- Charge Redistribution
- Many new architectures are possible and some may be much better than the best currently available
- All have perfect performance if parasitic and matching performance are ignored !
- Major challenge is in determining appropriate architecture and managing the parasitics

Nonideal Effects of Concern

- Matching
- Parasitic Capacitances (including Charge injection)
- Loading
- Nonlinearities
- Interconnect resistors
- Noise
- Speed
- Jitter
- Temperature Effects
- Aging
- Package stress

Observations

- Experienced Designers/Companies often produce superior data converter products
- Essentially all companies have access to the same literature, regularly reverse engineer successful competitors products and key benefits in successful competitors products are generally not locked up in patents
- High-end designs(speed and resolution) may get attention in the peer community but practical moderate performance converters usually make the cash flow
- Area (from a silicon cost viewpoint) is usually not the driving factor in high-end designs where attractive price/mfg cost ratios are common
- Considerable ongoing demand for data converter designers particularly in ASICs where DAC optimized for specific application

 X_{IN} is decoded to close one switch

Basic R-String DAC including Logic to Control Switches

Current Steering

Current Steering

Inherently Insensitive to Nonlinearities in Switches and Resistors

- Termed "top plate switching"
- Thermometer coded
- Based upon unary cell
- Speed limited by Op Amp and clock transients

Unary bit cell

Current Steering

Inherently Insensitive to Nonlinearities in Switches and Resistors Smaller ON resistance and less phase-shift from clock edges

- Termed "bottom plate switching"
- Thermometer coded
- Based upon unary cell
- Speed limited by Op Amp

- Unary bit cells usually bundled to make resistors
- Same number of unary cells needed as for thermometer coded structure
- Need for decoder eliminated !
- DNL may be a major problem
- INL performance about same as thermometer coded if same unit resistors used
- Sizing and layout of switches is critical

Observe thermometer coding and binary weighted both offer some major advantages and some major limitations

By superposition:

ion:
\n
$$
V_{OUT} = V_{REF} d_3 \cdot \frac{1}{2} + V_{REF} d_2 \cdot \frac{1}{4} + V_{REF} d_1 \cdot \frac{1}{8} + V_{REF} d_0 \cdot \frac{1}{16} = V_{REF} \sum_{k=0}^{3} \frac{d_k}{2^{4-k}} = V_{REF} \sum_{k=1}^{4} \frac{d_{4-k}}{2^{k}}
$$

R-2R Resistor Arrays

Charge Redistribution $\vec{X}_{IN} \rightarrow$ DAC \rightarrow

$$
Q_{SET} = V_{REF} \sum_{i=0}^{n-1} d_i \frac{C}{2^{n-i}}
$$

$$
Q_{RDIS} = V_{OUT} \left(\sum_{i=0}^{n-1} C_i + \left[C_0 \right] \right) = V_{OUT} \left(\sum_{i=0}^{n-1} \frac{C}{2^{n-i}} + \left[\frac{C}{2^n} \right] \right) = V_{OUT} C
$$

 $\mathcal{Q}_{\scriptscriptstyle SET}$ $=$ $\mathcal{Q}_{\scriptscriptstyle RDIS}$

$$
V_{REF} \sum_{i=0}^{n-1} d_i \frac{C}{2^{n-i}} = V_{OUT} C
$$

$$
V_{OUT} = V_{REF} \sum_{i=0}^{n-1} \frac{d_i}{2^{n-i}}
$$

MDAC

$$
V_{\text{OUT}} = V_{\text{REF}} \bullet \left[\vec{D}_{\text{IN}} \right]_{\text{DECIMAL}}
$$

- Some define MDACs to be DAC structures that have current outputs
- Many DAC structures can perform well as a MDAC (possibly one quadrant)
- Performance of some DAC structures limited if V_{RFF} is varied

Single Slope

Single-Slope DAC

Dual Slope

Conceptual

- **□ Simple structure**
- \Box Inherently monotone
- **Q** Very low DNL
- **Q** Potential for being very fast
- **Q** Low Power Dissipation
- **□ Widely Used Approach** (with appropriate considerations)

Challenges:

- Managing INL
- Large number of devices for n large (2^n) or 2^{n+1} lines)
- **Decoder**
- Routing thermometer/bubble clocks
- Transients during Boolean transitions
- Switch implementation
- Thevenin impedance facing V_{OUT} highly code dependent

Practical level shift

Switch Implementation

Other switch structures (such as bootstrapped switch) used but not for basic string DACs

Switch Assignment

Switch Impedances

Switch Parasitics

- C_{BD} and C_{BS} can be significant and cause rise-fall times to be position dependent
- \mathbf{C}_{GDOL} can cause "kickback" or feed-forward
- C_{GS} can slow turn-on and turn-off time of switch

Additional Challenges:

- Capacitance on V_{OUT} can be large
	- larger for p-channel devices
	- even larger for TG switches
- Switch impedances position dependent
- Kickback from switches to R-string
- Capacitance on each node (though small) of Rstring from switch
- Thevenin impedance facing V_{OUT} highly code dependent

Additional Challenges

- Delay in Decoder may be significant
- Delay in Decoder may be previous code and current code dependent
- Intermediate undesired Boolean outputs may occur
	- o These may cause undesired opening and closing of switches
	- o Could momentarily short out taps on R-string
	- o Could introduce transients on all nodes of R-string that are code and previous code dependent

Capacitive loading due to switches

- Uses matrix decoder as analog MUX
- Implements binary to decimal conversion with pass transistor analog logic
- Very structured layout
- Interconnection points are switches (combination of n-channel and p-channel)

Challenges

- Still many signals to route
- Large capacitance on V_{OUT} (over 2^{n+1}) diff caps)
- Multiple previous code dependencies cause output transition time to be quite unpredictable
- Considerable transients introduced on R-string

Parasitic Capacitances in Tree Decoder

Assume all C's initially with 0V Red denotes V_3 , black denotes 0V, Purple some other voltage

Previous-Code Dependent Settling

Assume all C's initially with 0V

Red denotes V_3 , green denotes V_6 , black denotes 0V, Purple some other v

Previous-Code Dependent Settling

Assume all C's initially with 0V

Red denotes V_{3} , green denotes V_{6} , black denotes 0V, Purple some other voltage

End of Lecture 12